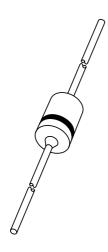
DISCRETE SEMICONDUCTORS

DATA SHEET



1N4148; 1N4448 High-speed diodes

Product specification Supersedes data of 2002 Jan 23 2004 Aug 10





High-speed diodes

1N4148; 1N4448

FEATURES

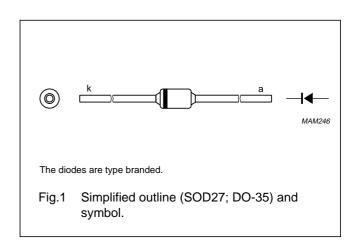
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- · General application
- Continuous reverse voltage: max. 100 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 450 mA.

APPLICATIONS

· High-speed switching.

DESCRIPTION

The 1N4148 and 1N4448 are high-speed switching diodes fabricated in planar technology, and encapsulated in hermetically sealed leaded glass SOD27 (DO-35) packages.



MARKING

TYPE NUMBER	MARKING CODE
1N4148	1N4148PH or 4148PH
1N4448	1N4448

ORDERING INFORMATION

TYPE NUMBER PACKAGE			
TIFE NOMBER			VERSION
1N4148	_	hermetically sealed glass package; axial leaded; 2 leads	SOD27
1N4448			

High-speed diodes

1N4148; 1N4448

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage		_	100	V
V _R	continuous reverse voltage		_	100	V
I _F	continuous forward current	see Fig.2; note 1	_	200	mA
I _{FRM}	repetitive peak forward current		_	450	mA
I _{FSM}	non-repetitive peak forward current	square wave; T _j = 25 °C prior to surge; see Fig.4			
		t = 1 μs	_	4	Α
		t = 1 ms	_	1	Α
		t = 1 s	_	0.5	Α
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	500	mW
T _{stg}	storage temperature		-65	+200	°C
T _i	junction temperature		_	200	°C

Note

1. Device mounted on an FR4 printed-circuit board; lead length 10 mm.

ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _F	forward voltage	see Fig.3			
	1N4148	I _F = 10 mA	_	1	V
	1N4448	I _F = 5 mA	0.62	0.72	V
		I _F = 100 mA	_	1	V
I _R	reverse current	V _R = 20 V; see Fig.5		25	nA
		V _R = 20 V; T _j = 150 °C; see Fig.5	_	50	μΑ
I _R	reverse current; 1N4448	$V_R = 20 \text{ V}; T_j = 100 ^{\circ}\text{C}; \text{ see Fig.5}$	_	3	μΑ
C _d	diode capacitance	$f = 1 \text{ MHz}$; $V_R = 0 \text{ V}$; see Fig.6	_	4	pF
t _{rr}	reverse recovery time	when switched from I_F = 10 mA to I_R = 60 mA; R_L = 100 Ω ; measured at I_R = 1 mA; see Fig.7	_	4	ns
V _{fr}	forward recovery voltage	when switched from $I_F = 50$ mA; $t_r = 20$ ns; see Fig.8	_	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-tp)}	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	lead length 10 mm; note 1	350	K/W

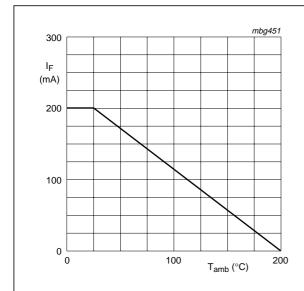
Note

1. Device mounted on a printed-circuit board without metallization pad.

High-speed diodes

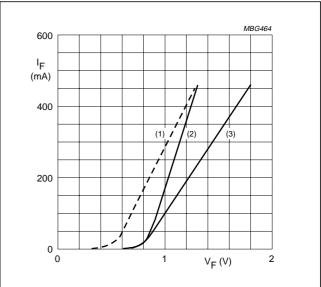
1N4148; 1N4448

GRAPHICAL DATA



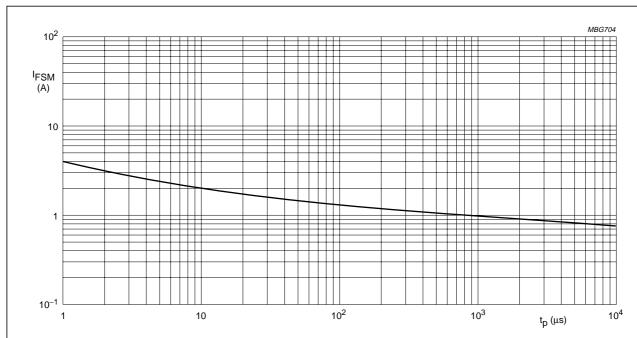
Device mounted on an FR4 printed-circuit board; lead length 10 mm.

Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.



- (1) $T_j = 175$ °C; typical values.
- (2) $T_j = 25$ °C; typical values.
- (3) $T_j = 25$ °C; maximum values.

Fig.3 Forward current as a function of forward voltage.



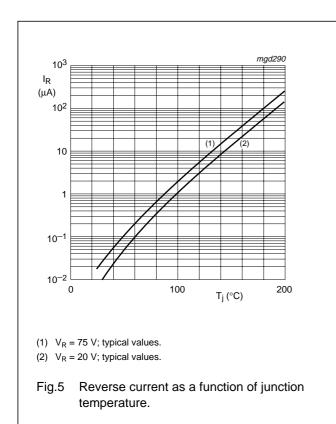
Based on square wave currents.

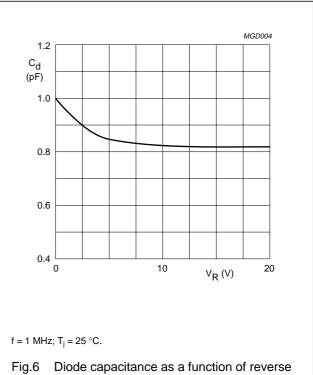
 $T_j = 25$ °C prior to surge.

Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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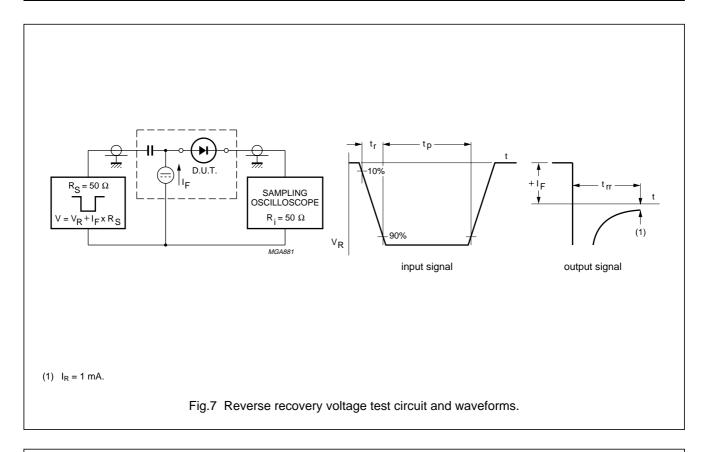


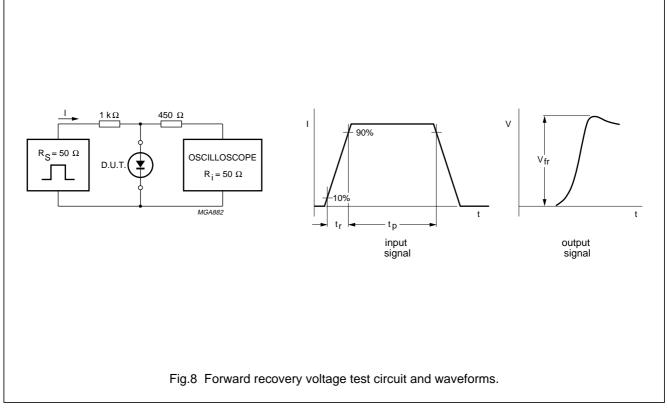
voltage; typical values.

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High-speed diodes

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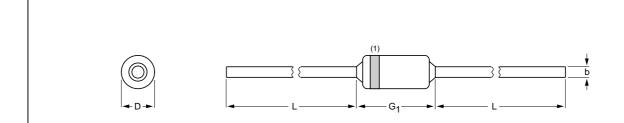
High-speed diodes

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PACKAGE OUTLINE

Hermetically sealed glass package; axial leaded; 2 leads

SOD27



DIMENSIONS (mm are the original dimensions)

UNIT	b	D	G ₁	L
	max.	max.	max.	min.
mm	0.56	1.85	4.25	25.4

0 1 2 mm scale

Note

1. The marking band indicates the cathode.

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOD27	A24	DO-35	SC-40			97-06-09

High-speed diodes

1N4148; 1N4448

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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